



Material Content Data Sheet



Sales Product Name				IPC100N04S5L-1R5		Issued		30. July 2019	
MA#				MA005122286					
Package				PG-TDSON-8-34		Weight*		112.75 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.110	0.98	0.98	9848	9848	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141		
	non noble metal	iron	7439-89-6	0.053	0.05		469		
	non noble metal	copper	7440-50-8	52.842	46.88	46.94	468674	469284	
	noble metal	gold	7440-57-5	0.046	0.04	0.04	410	410	
wire	organic material	carbon black	1333-86-4	0.075	0.07		667		
encapsulation	plastics	epoxy resin	-	5.942	5.27		52705		
	inorganic material	silicondioxide	60676-86-0	31.592	28.02	33.36	280205	333577	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13959	13959	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1856	1856	
solder	non noble metal	tin	7440-31-5	0.030	0.03		264		
	noble metal	silver	7440-22-4	0.037	0.03		330		
	non noble metal	lead	7439-92-1	1.422	1.26	1.32	12612	13206	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
heat sink clip	non noble metal	iron	7439-89-6	0.017	0.01		149		
	non noble metal	copper	7440-50-8	16.828	14.92	14.93	149250	149444	
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5667	5667	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2745	2749	
	*deviation < 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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